

## L-Band Medium & High Power GaAs FET

#### **FEATURES**

• High Output Power: P<sub>1dB</sub>=32.5dBm (Typ.)

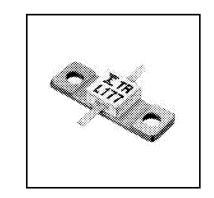
High Gain: G<sub>1dB</sub>=12.5dB (Typ.)
High PAE: η<sub>add</sub>=46% (Typ.)

· Proven Reliability

· Hermetically Sealed Package

### DESCRIPTION

The FLL177ME is a Power GaAs FET that is specifically designed to provide high power at L-Band frequencies with gain, linearity and efficiency superior to that of silicon devices. The performance in multitone environments for Class AB operation make them ideally suited for base station applications. This device is assembled in hermetic metal/ceramic package.



Fujitsu's stringent Quality Assurance Program assures the highest reliability and consistent performance.

## ABSOLUTE MAXIMUM RATING (Ambient Temperature Ta=25°C)

Item	Symbol	Condition	Rating	Unit	
Drain-Source Voltage	V <sub>DS</sub>		15	V	
Gate-Source Voltage	VGS		-5	V	
Total Power Dissipation	Pt	T <sub>C</sub> = 25°C	7.5	W	
Storage Temperature	T <sub>stg</sub>		-65 to +175	°C	
Channel Temperature	T <sub>ch</sub>		175	°C	

Fujitsu recommends the following conditions for the reliable operation of  ${\tt GaAs}$  FETs:

- 1. The drain-source operating voltage (V<sub>DS</sub>) should not exceed 10 volts.
- 2. The forward and reverse gate currents should not exceed 9.6 and -1.0 mA respectively with gate resistance of  $200\Omega$ .
- 3. The operating channel temperature (T<sub>ch</sub>) should not exceed 145°C.

#### **ELECTRICAL CHARACTERISTICS (Ambient Temperature Ta=25°C)**

lk a see	Company	Tool Oomalitions	Limit			11	
ltem	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Saturated Drain Current	IDSS	$V_{DS} = 5V$ , $V_{GS} = 0V$	-	600	900	mA	
Transconductance	9m	$V_{DS} = 5V, I_{DS} = 400 \text{mA}$	_	300	-	mS	
Pinch-off Voltage	۷p	$V_{DS} = 5V$ , $I_{DS} = 30$ mA	-1.0	-2.0	-3.5	V	
Gate Source Breakdown Voltage	VGSO	IGS = -30μA	-5	-	-	V	
Output Power at 1dB G.C.P.	P <sub>1dB</sub>		31.5	32.5	-	dBm	
Power Gain at 1dB G.C.P.	G <sub>1dB</sub>	V <sub>DS</sub> = 10V I <sub>DS</sub> ≈ 0.6I <sub>DSS</sub> (Typ.), f = 2.3GHz	11.5	12.5	-	dB	
Power-added Efficiency	ๆadd		-	46	-	%	
Thermal Resistance	R <sub>th</sub>	Channel to Case	-	15	20	°C/W	

**CASE STYLE:** ME

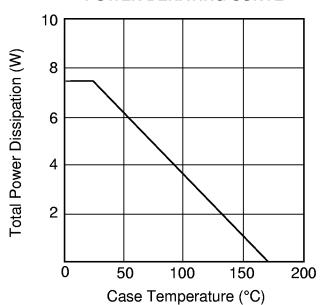
G.C.P.: Gain Compression Point



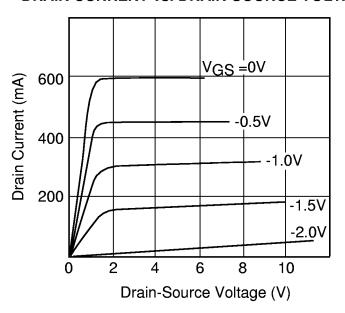
# FLL177ME

L-Band Medium & High Power GaAs FET

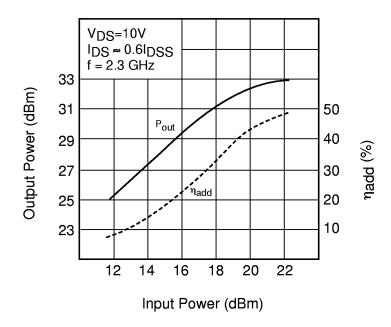
#### **POWER DERATING CURVE**



### **DRAIN CURRENT vs. DRAIN-SOURCE VOLTAGE**

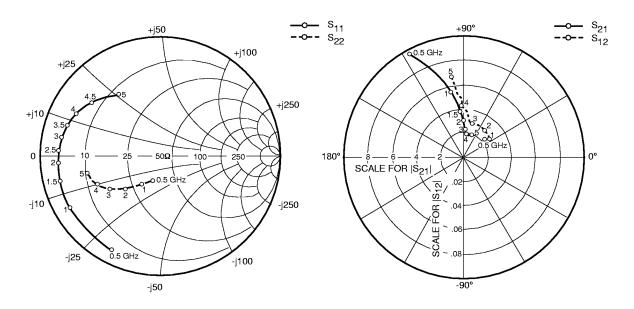


#### **OUTPUT POWER vs. INPUT POWER**





# L-Band Medium & High Power GaAs FET



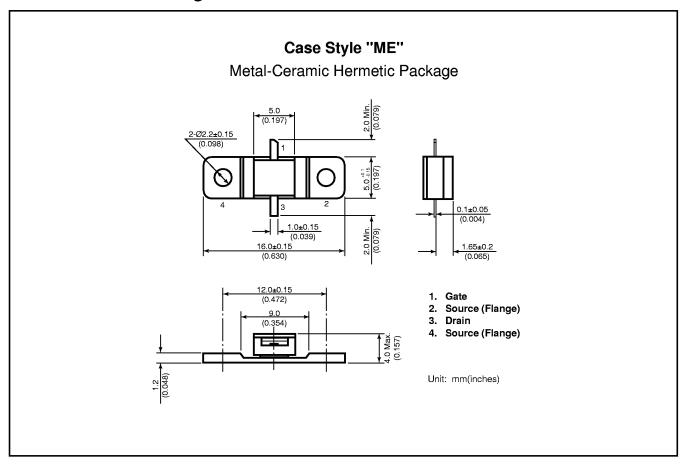
#### S-PARAMETERS

 $V_{DS} = 10V, I_{DS} = 360mA$ 

FREQUENCY	S	11	S2	S21		S12		S22	
(MHZ)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG	
500	.893	-117.6	9.628	117.9	.023	40.5	.219	-106.3	
1000	.865	-150.2	5.465	101.7	.025	36.1	.277	-123.1	
1500	.857	-165.4	3.853	95.3	.027	42.5	.337	-130.2	
2000	.852	-175.7	2.986	90.4	.028	52.6	.399	-136.1	
2500	.848	176.7	2.470	88.0	.029	65.6	.447	-140.5	
3000	.836	169.2	2.204	86.2	.028	76.7	.502	-145.6	
3500	.816	161.9	1.914	83.8	.037	85.1	.543	-151.0	
4000	.784	153.4	2.026	81.6	.042	92.5	.566	-154.8	
4500	.724	141.8	1.868	74.5	.048	91.8	.599	-158.9	
5000	.618	124.4	2.005	67.7	.067	99.0	.616	-166.0	



## L-Band Medium & High Power GaAs FET



## For further information please contact:

### FUJITSU COMPOUND SEMICONDUCTOR, INC.

2355 Zanker Rd.

San Jose, CA 95131-1138, U.S.A.

Phone: (408) 232-9500 FAX: (408) 428-9111 www.fcsi.fujitsu.com

#### FUJITSU MICROELECTRONICS, LTD.

Compound Semiconductor Division Network House Norreys Drive Maidenhead, Berkshire SL6 4FJ Phone:+44 (0)1628 504800 FAX:+44 (0)1628 504888

#### **CAUTION**

Fujitsu Compound Semiconductor Products contain **gallium arsenide** (**GaAs**) which can be hazardous to the human body and the environment. For safety, observe the following procedures:

- Do not put these products into the mouth.
- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.
- Observe government laws and company regulations when discarding this product. This product must be discarded in accordance with methods specified by applicable hazardous waste procedures.

Fujitsu Limited reserves the right to change products and specifications without notice. The information does not convey any license under rights of Fujitsu Limited or others.

© 1998 FUJITSU COMPOUND SEMICONDUCTOR, INC.

Printed in U.S.A. FCSI0598M200

